

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	115	"5218344"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/17 10:51
S2	43	"5399903"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/15 18:50
S3	934	(solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/09 14:12
S4	56	(solder adj1 mask) and (trench or recess or cavity) and MCM	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/15 18:54
S6	5	(solder adj1 mask) and (solder adj1 mask adj1 (trench or recess or cavity))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/15 18:55
S7	41	"5579207"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/17 10:52
S8	2	"6288909"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/17 10:52
S9	3	("4857989" "4926240" "5091770").PN. OR ("6614122").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/02/09 13:57
S15	4	361/743 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/10 15:50
S16	1	361/745 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/09 14:15

S17	20	361/748 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/09 14:16
S18	37	361/749 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/09 14:16
S19	4	361/750 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/09 14:16
S20	7	361/751 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/09 14:16
S22	46	361/761 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/09 14:17
S23	25	361/762 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/09 14:18
S24	45	361/764 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/09 14:18
S25	12	361/736 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/09 14:18
S26	12	361/728 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/09 14:19
S27	79	174/260 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/10 14:22

S28	48	174/250 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/10 14:39
S29	22	174/263 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/10 14:56
S30	55	174/262 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/10 14:58
S31	41	174/52.2 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/10 15:35
S34	3	(solder adj1 mask adj1 (trench or recess or cavity)) and mold\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/31 16:55
S36	2	(solder adj1 mask adj1 (trench or recess or cavity)) and underfill	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/10 15:08
S37	6	(solder adj1 mask adj1 (trench or recess or cavity))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/10 15:10
S38	47	("3657610" "4191905" "4266156" "4405875" "4604644" "4661192" "4699682" "4734608" "4736128" "4737742" "4864470" "4993000" "5014111" "5090119" "5095240" "5120678" "5252882" "5281883" "5359494" "5390401" "5438305" "5459368" "5471722" "5504980" "5900581").PN. OR ("5969461"), URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/02/10 15:18

S39	72	361/760 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/10 15:25
S40	90	174/52.2 and SAW	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/10 15:35
S41	56	174/52.2 and SAW and mold\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/10 15:35
S42	23	("4218701" "4509096" "4604644" "4725924" "4734818").PN. OR ("4864470"). URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/02/10 15:46
S43	2	310/313R and (solder adj1 mask)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/10 15:50
S44	0	2003/0218872	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/15 14:13
S45	2	"20030218872"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/15 14:13
S46	7	(solder adj1 mask adj1 (trench or recess or cavity)) and ((circuit adj1 board) or (substrate))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/31 17:02
S47	1	"20030104657"	US-PGPUB	OR	OFF	2005/03/31 17:02